

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ0506NS	**Issued**	08. April 2022
MA#	MA005711599		
Package	PG-TSDSON-8-25	**Weight***	34.37 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.182	0.53	0.53	5294	5294
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		106	
	non noble metal	zinc	7440-66-6	0.015	0.04		423	
	non noble metal	iron	7439-89-6	0.291	0.85		8458	
	non noble metal	copper	7440-50-8	11.804	34.34	35.24	343422	352409
wire	non noble metal	copper	7440-50-8	0.014	0.04	0.04	410	410
encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1064	
	plastics	epoxy resin	-	1.884	5.48		54806	
	inorganic material	silicondioxide	60676-86-0	16.369	47.63	53.22	476226	532096
leadfinish	non noble metal	tin	7440-31-5	0.395	1.15	1.15	11500	11500
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	591	591
solder	non noble metal	tin	7440-31-5	0.006	0.02		187	
	noble metal	silver	7440-22-4	0.008	0.02		234	
	non noble metal	lead	7439-92-1	0.307	0.89	0.93	8935	9356
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			27	
	non noble metal	zinc	7440-66-6	0.004	0.01		106	
	non noble metal	iron	7439-89-6	0.073	0.21		2120	
	non noble metal	copper	7440-50-8	2.959	8.61	8.83	86091	88344
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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